



<p style="text-align: right;">DEC 19 2003</p> <p style="text-align: right;">PATENT & TRADEMARK OFFICE</p> <p>LIST OF REFERENCES CITED BY APPLICANT (Use several sheets if necessary)</p>	ATTY DOCKET NO.	APPLICATION NO
	7426-083-999	10/705,706
	APPLICANT	
	Fukutomi <i>et al.</i>	
FILING DATE	GROUP	2813
November 10, 2003	To be assigned	

U.S. PATENT DOCUMENTS

FOREIGN PATENT DOCUMENTS

OTHER REFERENCES (Including Author, Title, Date, Pertinent Pages, Etc.)

EXAMINER <u>haesa Solberg</u>	DATE CONSIDERED <u>2/6/05</u>
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*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

LIST OF REFERENCES CITED BY APPLICANT
(Use several sheets if necessary)

ATTY DOCKET NO.	APPLICATION NO
7426-083-999	To be assigned
APPLICANT Fukutomi <i>et al.</i>	10705706
FILING DATE November 10, 2003	GROUP 2-813 To be assigned

U.S. PATENT DOCUMENTS

*EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
RL	A01 5,579,207	11/01/96	Hayden <i>et al.</i>			
RL	A02 5,467,252	11/01/95	Nomi <i>et al.</i>			
RL	A03 5,399,903	03/21/95	Rostoker <i>et al.</i>			
RL	A04 5,381,039	01/01/95	Morrison			
RL	A05 5,216,278	06/01/93	Lin <i>et al.</i>			
RL	A06 5,173,766	12/22/92	Long <i>et al.</i>			
RL	A07 4,975,765	12/04/90	Ackermann <i>et al.</i>			
RL	A08 4,688,150	08/18/87	Peterson			
RL	A09 4,376,287	03/01/83	Sechi			
RL	A10 3,878,555	04/01/75	Freitag <i>et al.</i>			
RL	A11 3,748,543	07/01/73	Roberson			

FOREIGN PATENT DOCUMENTS

	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION
						YES
RL	A12 JP 6053383	02/25/94	JAPAN			X
RL	A13 JP 5-129473	05/25/93	JAPAN			X
RL	A14 WO 92/21150	11/26/92	PCT			X
RL	A15 JP 4277636	10/02/92	JAPAN			X
RL	A16 JP 4072658	03/06/92	JAPAN			X
RL	A17 JP 4-26545	03/03/92	JAPAN			
RL	A18 JP 3094459	04/19/91	JAPAN			X
RL	A19 JP 3094430	04/19/91	JAPAN			X
RL	A20 WO 90/13991	11/15/90	PCT/US90/01828			
RL	A21 EP 0391790 A1	10/10/90	EUROPE			
RL	A22 JP 2153542	06/13/90	JAPAN			X
RL	A23 JP 1289273	11/21/89	JAPAN			X
RL	A24 JP 61222151	10/02/86	JAPAN			X
RL	A25 JP 60160624	08/22/85	JAPAN			X
RL	A26 JP 59231825	12/26/84	JAPAN			X
RL	A27 59-208756	11/27/84	JAPAN			X
RL	A28 JP 59043554	03/10/84	JAPAN			X
RL	A29 EP 0 091 072 A	10/12/83	EUROPE			

OTHER REFERENCES (Including Author, Title, Date, Pertinent Pages, Etc.)		
<i>YD</i>	A30	Matsuo <i>et al.</i> , "Smallest Flip-Chip-Like Package 'Chip Scale Package (CSP)", The Second VLS Packaging Workshop of Japan 1994
<i>YD</i>	A31	Nikkei Materials & Technology 94.4 (No. 140)
<i>RL</i>	A32	Tummala <i>et al.</i> ; Microelectronics Packaging Handbook: Semiconductor Packaging Second Edition Part II
EXAMINER	<i>hause Salesky</i>	
	DATE CONSIDERED <i>2/6/05</i>	
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